

## Status of PASTA Testing and Evaluation in Giessen:

### Preparation of FE PCB in 3 stages:

1) powering only PCB: for verification of start-up powering (i.e. shortcuts) and testing of fan-out bonding due to non-trivial bonding scheme of back-end pads. Only CLK pads connected. PCB ordered, lead time ~1 week. (RS)

2) in parallel design of more complex break-out PCB with all FE-connections wired to pinheader and space for Baby sensor. This PCB is thought as plug-in onto mother boards with varying functionalities. In this way, a standardized and fast mounting and bonding of the FE-carrier can be achieved independent of implemented features.

The mother boards can be produced cheap and quickly due to decoupling of technology from FE carrier.

Several versions of mother boards: w/o and w/ Vregs, DCDC, buffers

availability: ~January..February

status: design started (TQ), actual fan-out routing and thus design freeze depending on bonding test evaluation of 1)

3) design of double sided FE module with Baby sensor: testing of galvanically decoupled operation.

status: design will start as soon as 1) and 2) have been evaluated

